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**(54) Title (EN):** HOT-STAMPED PART AND MANUFACTURING METHOD THEREFOR

**(54) Title (FR):** PIÈCE ESTAMPÉE À CHAUD ET SON PROCÉDÉ DE FABRICATION

**(54) Title (KO):** 핫 스탬핑 부품 및 그 제조방법

**(57) Abstract:**

**(EN):** A hot-stamped part according to an embodiment of the present invention comprises, as a base layer, a steel comprising: 0.28-0.38 wt% of carbon (C); 0.1-0.4 wt% of silicon (Si); 1.2-2.0 wt% of manganese (Mn); from greater than 0 to 0.020 wt% of phosphorus (P); from greater than 0 to 0.003 wt% of sulfur (S); 0.1-0.5 wt% of chromium (Cr); 0.0015-0.0040 wt% of boron (B); 0.025-0.05 wt% of titanium (Ti); and the remainder of iron (Fe) and inevitable impurities, wherein the microstructure of the base layer is full martensite.

**(FR):** La présente invention concerne, selon un mode de réalisation, une pièce estampée à chaud comprenant, en tant que couche de base, un acier comprenant : de 0,28 à 0,38 % en poids de carbone (C) ; de 0,1 à 0,4 % en poids de silicium (Si) ; de 1,2 à 2,0 % en poids de manganèse (Mn) ; de plus de 0 à 0,020 % en poids de phosphore (P) ; de plus de 0 à 0,003 % en poids de soufre (S) ; de 0,1 à 0,5 % en poids de chrome (Cr) ; de 0,0015 à 0,0040 % en poids de bore (B) ; de 0,025 à 0,05 % en poids de titane (Ti) ; et le reste étant composé de fer (Fe) et d'impuretés inévitables, la microstructure de la couche de base étant intégralement composée de martensite.

**(KO):** 본 발명의 일 실시예에 따른 핫 스탬핑 부품은 탄소(C): 0.28 ~ 0.38 중량%, 규소(Si): 0.1 ~ 0.4 중량%, 망간(Mn): 1.2 ~ 2.0 중량%, 인(P): 0 초과 0.020 중량% 이하, 황(S): 0 초과 0.003 중량% 이하, 크롬(Cr): 0.1 ~ 0.5 중량%, 붕소(B):

0.0015 ~ 0.0040 중량%, 티타늄(Ti): 0.025 ~ 0.05 중량%, 및 잔부의 철(Fe)과 불가피한 불순물로 조성되는 강재를 소지층으로 포함하며, 상기 소지층의 미세조직은 풀 마르텐사이트(full martensite)이다.

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